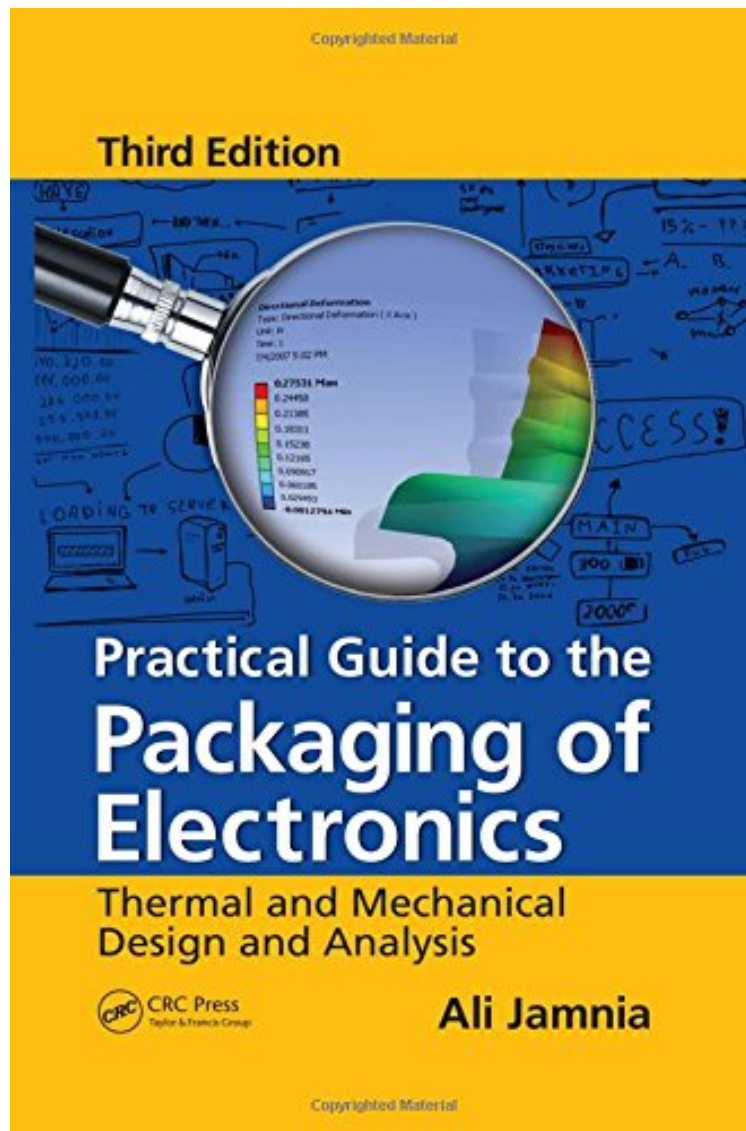


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# Practical Guide to the Packaging of Electronics: Thermal and Mechanical Design and Analysis, Third Edition

Ali Jamnia

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Successfully Estimate the Thermal and Mechanical Characteristics of Electronics Systems A definitive guide for practitioners new to the field or requiring a refresher course, Practical Guide to the Packaging of Electronics: Thermal and Mechanical Design and Analysis, Third Edition provides an understanding of system failures and helps identify the areas where they can occur. Specifically designed for the mechanical, electrical, or quality engineer, the book addresses engineering issues involved in electronics packaging and provides the basics needed to design a new system or troubleshoot a current one. Updated to reflect recent developments in the field, this latest edition adds two new chapters on acoustic and reliability fundamentals, and contains more information on electrical failures and causes. It also includes tools for understanding heat transfer, shock, and vibration. Additionally, the author: Addresses various cross-discipline issues in the design of electromechanical products Provides a solid foundation for heat transfer, vibration, and life expectancy calculations Identifies reliability issues and concerns Develops the ability to conduct a more thorough analysis for the final design Includes design tips and guidelines for each aspect of electronics packaging Practical Guide to the Packaging of Electronics: Thermal and Mechanical Design and Analysis, Third Edition explains the mechanical and thermal/fluid aspects of electronic product design and offers a basic understanding of electronics packaging design issues. Defining the material in-depth, it also describes system design guidelines and identifies reliability concerns for practitioners in mechanical, electrical or quality engineering.

"This book is intended for a hands-on engineer who needs back-of-the-envelope tools to develop design parameters and develop a means to conduct sanity checks. The true value of the book, however, is to raise the awareness of the design team on various aspects of the design that leads to developing a more reliable product." James Feine, President, USI Ultrasonic, Houston, Texas, USA  
About the Author Ali Jamnia enjoys teaching and mentoring junior engineers. His primary expertise lies in electromechanical systems design and development. In addition, he enjoys conducting analysis of various engineering problems using numerical approximations and computer simulations. Dr. Jamnia has focused on the issues of electronics packaging since the early 1990s, and since 1995, has been involved with the development of innovative electronics systems to aid individuals with either physical or cognitive disabilities. In fact, his prime achievement has been the development of a specialized computer system called the Learning Station™ - used as a teaching tool for individuals with cognitive disabilities.